


IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of attaching a semiconductor die to a lead frame comprising:
providing a source of snap curable adhesive;
providing a source of lead frames, each lead frame having an attaching surface;
providing a source of semiconductor die, each semiconductor die having an active surface;
heating at least one of the semiconductor die;
applying said snap curable adhesive to portions of one of the lead frames; and
contacting said active surface of one of the heated semiconductor die with said portions of one of the lead frames having said snap curable adhesive thereon.

No sequence

2. (Canceled)

 3. (Original) The method of claim 1, wherein said snap curable adhesive includes a snap curable epoxy having a cure time of about one second.

4. (Original) The method of claim 1, wherein said snap curable adhesive includes an adhesive having a cure time of substantially one minute or less.

5. (Original) The method of claim 1, wherein said snap curable adhesive is applied to the portions of said one of the lead frames using a roller.

6. (Previously Presented) A method of attaching a semiconductor die to a lead frame comprising:

providing a source of snap curable adhesive;

providing a source of lead frames, each lead frame having an attaching surface;

providing a source of semiconductor die, each semiconductor die having an active surface;

applying said snap curable adhesive to portions of the active surface of one of the semiconductor die; and

contacting said snap curable adhesive with portions of one of said lead frames.

7. (Original) The method of claim 6, wherein said snap curable adhesive includes an adhesive having a curing time of about one second or less.

8. (Previously Presented) The method of claim 6, wherein said snap curable adhesive is applied to said active surface of said one of the semiconductor die in a predetermined pattern.